

VQFN-8

Surface Mount Device
Small Outline No-Lead
Exposed pad

Short Product Overview

May 2010

Chip Card & Security

VQFN-8 Short Product Overview	Ref.: Chip_Card_Product_Overview_11/09
Revision History: Current Version 05.10	
Previous Releases:	
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Important: Further information is confidential and on request. Please contact:
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Edition 2010

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Chip Card & Security
81726 Munich, Germany
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Product name	VQFN-8
Picture	
Product description	Surface Mount Device Small Outline No-Lead Exposed pad
Typical Applications	Embedded Security Authentication Ingetrity
Pitch	1.27 mm
Dimensions	Body: 5 x 6 mm
Thickness	max. 900µm
Contact Surface	NiPdAuAg
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	-
Derivatives	-

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